Docket No.: 50090-295



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

h re Application of

: Response Under 37 CFR 1.116 - Expedited Procedure

Masaki WATANABE, et al.

Serial No.: 09/846,272

Group Art Unit: 2827

Filed: May 02, 2001

Examiner: Lourdes C. Cruz

For:

SEMICONDUCTOR DEVICE HAVING CAPACITORS FOR REDUCING POWER SOURCE NOISE

Box AF

THE COMMISSIONER FOR PATENTS AND TRADEMARKS

Washington, DC 20231

Dear Sir:

Transmitted herewith is an Amendment in the above identified application.

No additional fee is required.

Applicant is entitled to small entity status under 37 CFR 1.27

Also attached:

The fee has been calculated as shown below:

	NO. OF CLAIMS	HIGHEST PREVIOUSLY PAID FOR	EXTRA CLAIMS	RATE	FEE
Total Claims	15	20	0	\$18.00 =	\$0.00
Independent Claims	3	3	0	\$84.00 =	\$0.00
		Multiple claims newly presented			\$0.00
		Fee for extension of time			\$0.00
					\$0.00
		Total of Above Calculations			\$0.00

Please charge my Deposit Account No. <u>500417</u> in the amount of \$0.00. An additional copy of this transmittal sheet is submitted herewith.

The Commissioner is hereby authorized to charge payment of any fees associated with this communication or credit any overpayment, to Deposit Account No. 500417, including any filing fees under 37 CFR 1.16 for presentation of extra claims and any patent application processing fees under 37 CFR 1.17.

Respectfully submitted,

MCDERMOTT, WILL & EMERY

Bernard P. Codd

Registration No. 46,429

APR 15 2003

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IR 1 LIMB Docket No.: 50090-295

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

: AMENDMENT UNDER 37 CFR § 1.116

EXPEDITED PROCEDURE

Masaki WATANABE, et al.

Serial No.: 09/846,272

Group Art Unit: 2827

Filed: May 02, 2001

Examiner: L.C. Cruz

For: SEMICONDUCTOR DEVICE HAVING CAPACITORS FOR REDUCING POWERS
SOURCE NOISE

AMENDMENT UNDER 37 CFR § 1.116

Box AF Commissioner for Patents Washington, DC 20231

Sir:

The following amendment and remarks are respectfully submitted in response to the Office Action dated January 14, 2003, pursuant to 37 CFR § 1.116.

IN THE CLAIMS:

Please amend claim 2 as follows:

- 2. (Twice Amended) A semiconductor device comprising:
- a BGA substrate having one principal plane furnished with a large number of solder balls;
- a first semiconductor chip including bumps and active regions, said bumps and active regions being formed on a first side of the semiconductor chip, said bumps serving as electrodes attached to another principal plane of said BGA substrate; and